C5020

Conductor

Description

C5020 is an unfritted lead, gold conductor. It is designed for application on top of a gold-based layer to increase thickness and solderability.In a single print and fire application on a gold base layer it yields a thick, dense film that is free from blisters, cracks, and other cosmetic defects.C5020 has good adhesion when printed over a gold base layer of Heraeus Au conductors. It is not designed to be used without a gold base layer.

Key Features

- Excellent choice for higher conductivity applications that require thick gold conductor

This picture does not show the packaging of C5020 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Conductivity	≤ 4.5 milliohms/square (FFT: 8 um)
Viscosity	35 – 55 Pas (25 °C, D = 75/s)
Alloy Ratio	100
Coverage	Approx. 50 cm2 / g (FFT: 8 µm)
Metal	Au

Recommended Processing Guide	
Printing Parameters	Print through a 200 – 325 mesh stainless steel screen. Level at room temperature for 10 minutes.
Printing Speed	Up to at least 10 cm / s
Drying Temperature	Dry at 125 – 150 °C for 10 – 20 minutes.
Process Temperature (TDS)	Fire at 550 – 950 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30 – 60 minutes
Film Thickness	6 – 10 µm
Recommended Thinner	HVS-100

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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All changes are based on information displayed using the template data_sheet/HET/TFM/print_data_sheet.html.twig.
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